

# 3.3 V ECL Programmable Delay Chip



## MC100EP195

The MC100EP195 is a Programmable Delay Chip (PDC) designed primarily for clock deskewing and timing adjustment. It provides variable delay of a differential NECL/PECL input transition.

The delay section consists of a programmable matrix of gates and multiplexers as shown in the logic diagram, Figure 3. The delay increment of the EP195 has a digitally selectable resolution of about 10 ps and a net range of up to 10.2 ns. The required delay is selected by the 10 data select inputs D[9:0] values and controlled by the LEN (pin 10). A LOW level on LEN allows a transparent LOAD mode of real time delay values by D[9:0]. A LOW to HIGH transition on LEN will LOCK and HOLD current values present against any subsequent changes in D[10:0]. The approximate delay values for varying tap numbers correlating to D0 (LSB) through D9 (MSB) are shown in Table 6 and Figure 4.

Because the EP195 is designed using a chain of multiplexers it has a fixed minimum delay of 2.2 ns. An additional pin D10 is provided for controlling Pins 14 and 15, CASCADE and  $\overline{\text{CASCADE}}$ , also latched by LEN, in cascading multiple PDCs for increased programmable range. The cascade logic allows full control of multiple PDCs. Switching devices from all “1” states on D[0:9] with SETMAX LOW to all “0” states on D[0:9] with SETMAX HIGH will increase the delay equivalent to “D0”, the minimum increment.

Select input pins D[10:0] may be threshold controlled by combinations of interconnects between  $V_{EF}$  (pin 7) and  $V_{CF}$  (pin 8) for LVCMOS, ECL, or LVTTTL level signals. For LVCMOS input levels, leave  $V_{CF}$  and  $V_{EF}$  open. For ECL operation, short  $V_{CF}$  and  $V_{EF}$  (Pins 7 and 8). For LVTTTL level operation, connect a 1.5 V supply reference to  $V_{CF}$  and leave open  $V_{EF}$  pin. The 1.5 V reference voltage to  $V_{CF}$  pin can be accomplished by placing a 2.2 k $\Omega$  resistor between  $V_{CF}$  and  $V_{EE}$  for a 3.3 V power supply.

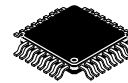
The  $V_{BB}$  pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to  $V_{BB}$  as a switching reference voltage.  $V_{BB}$  may also rebias AC coupled inputs. When used, decouple  $V_{BB}$  and  $V_{CC}$  via a 0.01  $\mu\text{F}$  capacitor and limit current sourcing or sinking to 0.5 mA. When not used,  $V_{BB}$  should be left open.

The 100 Series contains temperature compensation.

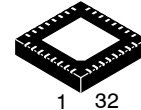
- Maximum Input Clock Frequency >1.2 GHz Typical
- Programmable Range: 0 ns to 10 ns
- Delay Range: 2.2 ns to 12.2 ns
- 10 ps Increments
- PECL Mode Operating Range:
  - $V_{CC} = 3.0 \text{ V to } 3.6 \text{ V with } V_{EE} = 0 \text{ V}$
- NECL Mode Operating Range:
  - $V_{CC} = 0 \text{ V with } V_{EE} = -3.0 \text{ V to } -3.6 \text{ V}$
- Open Input Default State
- Safety Clamp on Inputs
- A Logic High on the  $\overline{\text{EN}}$  Pin Will Force Q to Logic Low
- D[10:0] Can Accept Either ECL, LVCMOS, or LVTTTL Inputs
- $V_{BB}$  Output Reference Voltage
- These are Pb-Free Devices

**ON Semiconductor®**

[www.onsemi.com](http://www.onsemi.com)

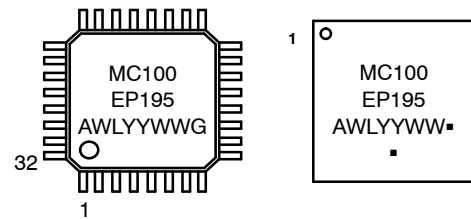


**LQFP-32  
FA SUFFIX  
CASE 561AB**



**QFN32  
MN SUFFIX  
CASE 488AM**

### MARKING DIAGRAMS\*



- A = Assembly Location
- WL, L = Wafer Lot
- YY, Y = Year
- WW, W = Work Week
- G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

\*For additional marking information, refer to Application Note [AND8002/D](#).

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 15 of this data sheet.

# MC100EP195

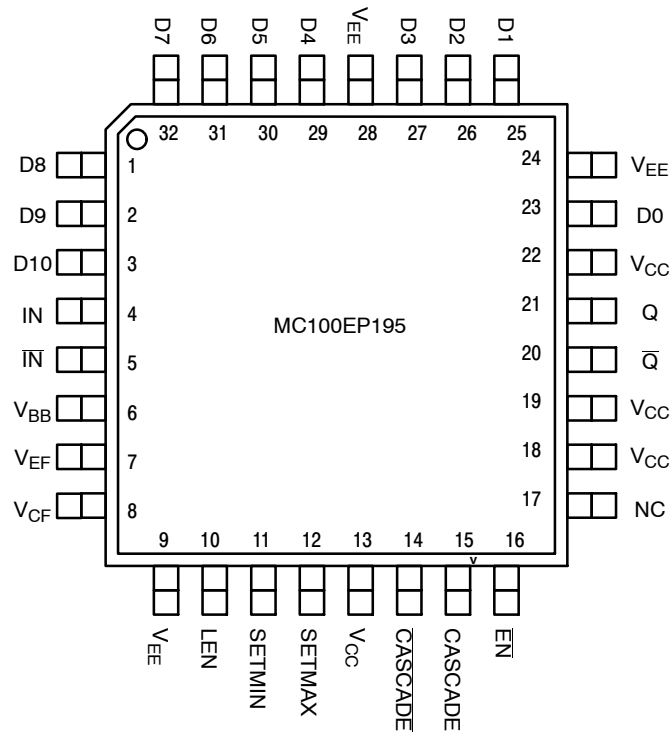


Figure 1. 32-Lead LQFP Pinout (Top View)

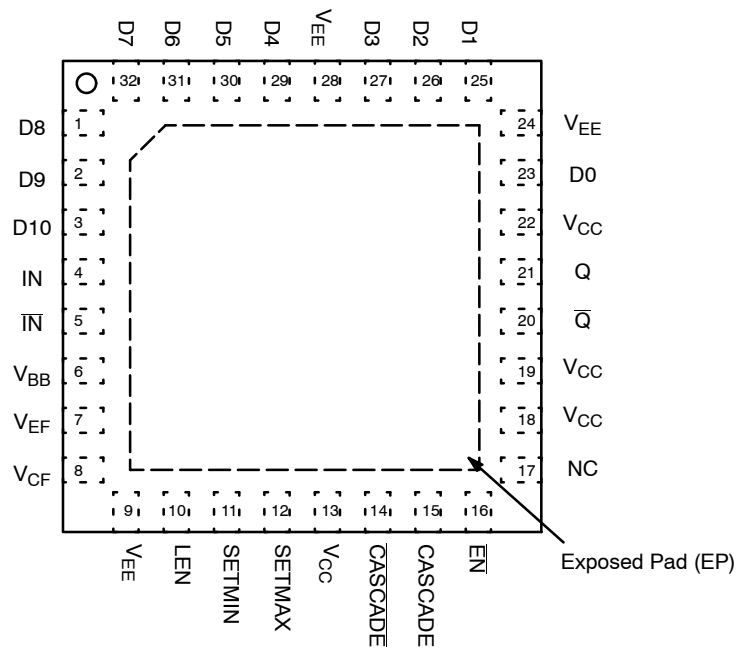


Figure 2. 32-Lead QFN (Top View)

# MC100EP195

**Table 1. PIN DESCRIPTION**

Pin	Name	I/O	Default State	Description
23, 25, 26, 27, 29, 30, 31, 32, 1, 2	D[0:9]	LVC MOS, LV TTL, ECL Input	Low	Single-Ended Parallel Data Inputs [0:9]. Internal 75 k $\Omega$ to V <sub>EE</sub> . (Note 1)
3	D[10]	LVC MOS, LV TTL, ECL Input	Low	Single-Ended CASCADE/CASCADE $\bar{E}$ Control Input. Internal 75 k $\Omega$ to V <sub>EE</sub> . (Note 1)
4	IN	ECL Input	Low	Noninverted Differential Input. Internal 75 k $\Omega$ to V <sub>EE</sub> .
5	$\bar{IN}$	ECL Input	High	Inverted Differential Input. Internal 75 k $\Omega$ to V <sub>EE</sub> and 36.5 k $\Omega$ to V <sub>CC</sub> .
6	V <sub>BB</sub>	-	-	ECL Reference Voltage Output
7	V <sub>EF</sub>	-	-	Reference Voltage for ECL Mode Connection
8	V <sub>CF</sub>	-	-	LVC MOS, ECL, OR LV TTL Input Mode Select
9, 24, 28	V <sub>EE</sub>	-	-	Negative Supply Voltage. All V <sub>EE</sub> Pins must be Externally Connected to Power Supply to Guarantee Proper Operation. (Note 2)
13, 18, 19, 22	V <sub>CC</sub>	-	-	Positive Supply Voltage. All V <sub>CC</sub> Pins must be externally Connected to Power Supply to Guarantee Proper Operation. (Note 2)
10	LEN	ECL Input	Low	Single-ended D pins LOAD / HOLD input. Internal 75 k $\Omega$ to V <sub>EE</sub> .
11	SETMIN	ECL Input	Low	Single-ended Minimum Delay Set Logic Input. Internal 75 k $\Omega$ to V <sub>EE</sub> . (Note 1)
12	SETMAX	ECL Input	Low	Single-ended Maximum Delay Set Logic Input. Internal 75 k $\Omega$ to V <sub>EE</sub> . (Note 1)
14	$\bar{CASCAD E}$	ECL Output	-	Inverted Differential Cascade Output for D[10]. Typically Terminated with 50 $\Omega$ to V <sub>TT</sub> = V <sub>CC</sub> - 2 V.
15	CASCADE	ECL Output	-	Noninverted Differential Cascade Output. for D[10] Typically Terminated with 50 $\Omega$ to V <sub>TT</sub> = V <sub>CC</sub> - 2 V.
16	$\bar{EN}$	ECL Input	Low	Single-ended Output Enable Pin. Internal 75 k $\Omega$ to V <sub>EE</sub> .
17	NC	-	-	No Connect. The NC Pin is Electrically Connected to the Die and "MUST BE" Left Open.
21	Q	ECL Output	-	Noninverted Differential Output. Typically Terminated with 50 $\Omega$ to V <sub>TT</sub> = V <sub>CC</sub> - 2 V.
20	$\bar{Q}$	ECL Output	-	Inverted Differential Output. Typically Terminated with 50 $\Omega$ to V <sub>TT</sub> = V <sub>CC</sub> - 2 V.

1. SETMIN will override SETMAX if both are high. SETMAX and SETMIN will override all D[0:10] inputs.
2. All V<sub>CC</sub> and V<sub>EE</sub> pins must be externally connected to Power Supply to guarantee proper operation.

# MC100EP195

**Table 2. CONTROL PIN**

Pin	State	Function
EN	LOW (Note 3)	Input Signal is Propagated to the Output
	HIGH	Output Holds Logic Low State
LEN	LOW (Note 3)	Transparent or LOAD mode for real time delay values present on D[0:10].
	HIGH	LOCK and HOLD mode for delay values on D[0:10]; further changes on D[0:10] are not recognized and do not affect delay.
SETMIN	LOW (Note 3)	Output Delay set by D[0:10]
	HIGH	Set Minimum Output Delay
SETMAX	LOW (Note 3)	Output Delay set by D[0:10]
	HIGH	Set Maximum Output Delay
D10	LOW (Note 3)	CASCADE Output LOW, CASCADE Output HIGH
	HIGH	CASCADE Output LOW, CASCADE Output HIGH

3. Internal pulldown resistor will provide a logic LOW if pin is left unconnected.

**Table 3. CONTROL D[0:10] INTERFACE**

$V_{CF}$	$V_{EF}$ Pin (Note 4)	ECL Mode
$V_{CF}$	No Connect	LVC MOS Mode
$V_{CF}$	1.5 V $\pm$ 100 mV	LVTTTL Mode (Note 5)

4. Short  $V_{CF}$  (pin 8) and  $V_{EF}$  (pin 7).

5. When Operating in LVTTTL Mode, the reference voltage can be provided by connecting an external resistor,  $R_{CF}$  (suggested resistor value is 2.2 k $\Omega$   $\pm$  5%), between  $V_{CF}$  and  $V_{EE}$  pins.

**Table 4. DATA INPUT ALLOWED OPERATING VOLTAGE MODE TABLE**

POWER SUPPLY	CONTROL DATA SELECT INPUTS PINS (D [0:10])			
	LVC MOS	LVTTTL	LVPECL	LVNECL
PECL Mode Operating Range	YES	YES	YES	N/A
NECL Mode Operating Range	N/A	N/A	N/A	YES

**Table 5. ATTRIBUTES**

Characteristics	Value
Internal Input Pulldown Resistor (R1)	75 k $\Omega$
ESD Protection Human Body Model Machine Model Charged Device Model	> 2 kV > 100 V > 2 kV
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 6)	Pb-Free Pkg
LQFP-32	Level 2
QFN-32	Level 1
Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count	1217 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

6. For additional information, see Application Note [AND8003/D](#).

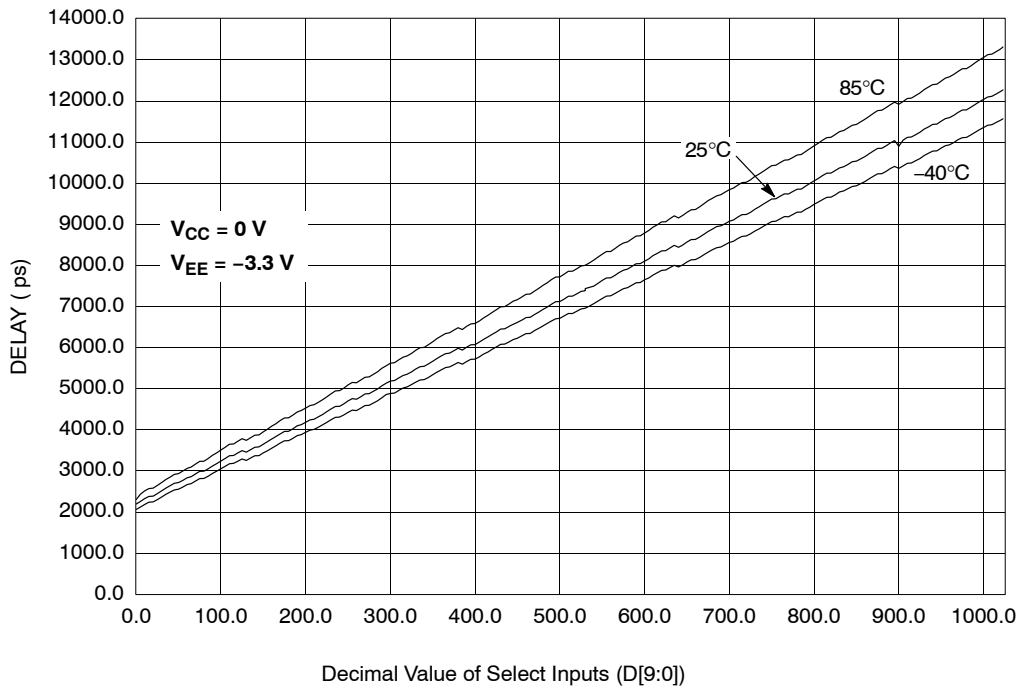


# MC100EP195

**Table 6. THEORETICAL DELAY VALUES**

D(9:0) Value	SETMIN	SETMAX	Programmable Delay*
XXXXXXXXXX	H	L	0 ps
000000000	L	L	0 ps
000000001	L	L	10 ps
000000010	L	L	20 ps
000000011	L	L	30 ps
000000100	L	L	40 ps
000000101	L	L	50 ps
000000110	L	L	60 ps
000000111	L	L	70 ps
000001000	L	L	80 ps
000010000	L	L	160 ps
000100000	L	L	320 ps
001000000	L	L	640 ps
010000000	L	L	1280 ps
100000000	L	L	5120 ps
111111111	L	L	10230 ps
XXXXXXXXXX	L	H	10240 ps

\*Fixed minimum delay not included.



**Figure 4. Measured Delay vs. Select Inputs**

# MC100EP195

**Table 7. MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
$V_{CC}$	Positive Mode Power Supply	$V_{EE} = 0\text{ V}$		6	V
$V_{EE}$	Negative Mode Power Supply	$V_{CC} = 0\text{ V}$		-6	V
$V_I$	Positive Mode Input Voltage	$V_{EE} = 0\text{ V}$	$V_I \leq V_{CC}$	6	V
	Negative Mode Input Voltage	$V_{CC} = 0\text{ V}$	$V_I \geq V_{EE}$	-6	V
$I_{out}$	Output Current	Continuous Surge		50	mA
				100	mA
$I_{BB}$	$V_{BB}$ Sink/Source			$\pm 0.5$	mA
$T_A$	Operating Temperature Range			-40 to +85	$^{\circ}\text{C}$
$T_{stg}$	Storage Temperature Range			-65 to +150	$^{\circ}\text{C}$
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm	LQFP-23	80	$^{\circ}\text{C}/\text{W}$
		500 lfpm	LQFP-23	55	$^{\circ}\text{C}/\text{W}$
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	LQFP-23	12 to 17	$^{\circ}\text{C}/\text{W}$
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm	QFN-32	31	$^{\circ}\text{C}/\text{W}$
		500 lfpm	QFN-32	27	$^{\circ}\text{C}/\text{W}$
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	2S2P	QFN-32	12	$^{\circ}\text{C}/\text{W}$
$T_{sol}$	Wave Solder	Pb-Free		265	$^{\circ}\text{C}$
		<2 to 3 sec @ 260 $^{\circ}\text{C}$			

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

# MC100EP195

**Table 8. 100EP DC CHARACTERISTICS, PECL**  $V_{CC} = 3.3\text{ V}$ ,  $V_{EE} = 0\text{ V}$  (Note 7)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Negative Power Supply Current	100	135	160	100	140	170	100	145	175	mA
$V_{OH}$	Output HIGH Voltage (Note 8)	2155	2280	2405	2155	2280	2405	2155	2280	2405	mV
$V_{OL}$	Output LOW Voltage (Note 8)	1305	1480	1605	1305	1480	1605	1305	1480	1605	mV
$V_{IH}$	Input HIGH Voltage (Single-Ended)										mV
	LVPECL	2075		2420	2075		2420	2075		2420	
	CMOS	2000		3300	2000		3300	2000		3300	
	TTL	2000		3300	2000		3300	2000		3300	
$V_{IL}$	Input LOW Voltage (Single-Ended)										mV
	LVPECL	1305		1675	1305		1675	1305		1675	
	CMOS	0		800	0		800	0		800	
	TTL	0		800	0		800	0		800	
$V_{BB}$	ECL Output Voltage Reference	1775	1875	1975	1775	1875	1975	1775	1875	1975	mV
$V_{CF}$	LVTTTL Mode Input Detect Voltage	1.4	1.5	1.6	1.4	1.5	1.6	1.4	1.5	1.6	V
$V_{EF}$	Reference Voltage for ECL Mode Connection	1920	2020	2120	1920	2020	2120	1920	2020	2120	mV
$V_{IHCMR}$	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 9)	2.0		3.3	2.0		3.3	2.0		3.3	V
$I_{IH}$	Input HIGH Current (@ $V_{IH}$ )			150			150			150	$\mu\text{A}$
$I_{IL}$	Input LOW Current (@ $V_{IL}$ )										$\mu\text{A}$
	$\overline{IN}$	0.5			0.5			0.5			
	$\overline{IN}$	-150			-150			-150			

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

7. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary +0.3 V to -0.3 V.

8. All loading with 50  $\Omega$  to  $V_{CC} - 2.0\text{ V}$ .

9.  $V_{IHCMR}$  min varies 1:1 with  $V_{EE}$ ,  $V_{IHCMR}$  max varies 1:1 with  $V_{CC}$ . The  $V_{IHCMR}$  range is referenced to the most positive side of the differential input signal.



# MC100EP195

**Table 9. 100EP DC CHARACTERISTICS, NECL**  $V_{CC} = 0\text{ V}$ ,  $V_{EE} = -3.3\text{ V}$  (Note 10)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Negative Power Supply Current (Note 11)	100	135	160	100	140	170	100	145	175	mA
$V_{OH}$	Output HIGH Voltage (Note 12)	-1145	-1020	-895	-1145	-1020	-895	-1145	-1020	-895	mV
$V_{OL}$	Output LOW Voltage (Note 12)	-1995	-1820	-1695	-1995	-1820	-1695	-1995	-1820	-1695	mV
$V_{IH}$	Input HIGH Voltage (Single-Ended) LVNECL	-1225		-880	-1225		-880	-1225		-880	mV
$V_{IL}$	Input LOW Voltage (Single-Ended) LVNECL	-1995		-1625	-1995		-1625	-1995		-1625	mV
$V_{BB}$	ECL Output Voltage Reference	-1525	-1425	-1325	-1525	-1425	-1325	-1525	-1425	-1325	mV
$V_{EF}$	Reference Voltage for ECL Mode Connection	-1380	-1280	-1180	-1380	-1280	-1180	-1380	-1280	-1180	mV
$V_{IHCMR}$	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 13)	$V_{EE}+2.0$		0.0	$V_{EE}+2.0$		0.0	$V_{EE}+2.0$		0.0	V
$I_{IH}$	Input HIGH Current (@ $V_{IH}$ )			150			150			150	$\mu\text{A}$
$I_{IL}$	Input LOW Current (@ $V_{IL}$ )		0.5 -150			0.5 -150			0.5 -150		$\mu\text{A}$

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

10. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary +0.3 V to -0.3 V.

11. Recommended  $V_{CC} - V_{EE}$  operation at  $3.0\text{ V} \leq 3.6\text{ V}$ .

12. All loading with  $50\ \Omega$  to  $V_{CC} - 2.0\text{ V}$ .

13.  $V_{IHCMR}$  min varies 1:1 with  $V_{EE}$ .  $V_{IHCMR}$  max varies 1:1 with  $V_{CC}$ . The  $V_{IHCMR}$  range is referenced to the most positive side of the differential input signal.

# MC100EP195

**Table 10. AC CHARACTERISTICS**  $V_{CC} = 0\text{ V}$ ;  $V_{EE} = -3.0\text{ V to }-3.6\text{ V}$  or  $V_{CC} = 3.0\text{ V to }3.6\text{ V}$ ;  $V_{EE} = 0\text{ V}$  (Note 14)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{max}$	Maximum Frequency		1.2			1.2			1.2		GHz
$t_{PLH}$ $t_{PHL}$	Propagation Delay IN to Q; D(0-10) = 0 IN to Q; D(0-10) = 1023 $\overline{EN}$ to Q; D(0-10) = 0 D0 to CASCADE	1650 9500 1600 300	2050 11500 2150 420	2450 13500 2600 500	1800 10000 1800 350	2200 12200 2300 450	2600 14000 2800 550	1950 10800 2000 425	2350 13300 2500 525	2750 15800 3000 625	ps
$t_{RANGE}$	Programmable Range $t_{PD}(\text{max}) - t_{PD}(\text{min})$	7850	9450		8200	10000		8850	10950		ps
$\Delta t$	Step Delay (Note 15) D0 High D1 High D2 High D3 High D4 High D5 High D6 High D7 High D8 High D9 High		13 27 44 90 130 312 590 1100 2250 4500			14 30 47 97 140 335 650 1180 2400 4800			41 100 145 360 690 1300 2650 5300		ps
mono	Monotonicity (Note 21)					TBD					
$t_{SKEW}$	Duty Cycle Skew (Note 16) $ t_{PHL} - t_{PLH} $		25			25			25		ps
$t_s$	Setup Time D to LEN D to IN (Note 17) EN to IN (Note 18)	200 300 300	0 140 150		200 300 300	0 160 170		200 300 300	0 180 180		ps
$t_h$	Hold Time LEN to D IN to $\overline{EN}$ (Note 19)	200 400	60 250		200 400	100 280		200 400	80 300		ps
$t_R$	Release Time $\overline{EN}$ to IN (Note 20) SET MAX to LEN SET MIN to LEN	150 400 350	-25 200 275		150 400 350	-75 250 200		150 400 350	-50 300 225		ps
$t_{jitter}$	RMS Random Clock Jitter @ 1.2 GHz IN to Q; D(0:10) = 0 or SETMIN IN to Q; D(0:10) = 1023 or SETMAX		0.86 0.89			1.16 1.09			1.12 1.02		ps
$V_{PP}$	Input Voltage Swing (Differential Configuration)	150	800	1200	150	800	1200	150	800	1200	mV
$t_r$ $t_f$	Output Rise/Fall Time @ 50 MHz 20-80% (Q) 20-80% (CASCADE)	85 100	100 140	135 200	85 110	110 150	135 200	95 130	125 170	155 220	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm.

14. Measured using a 750 mV source, 50% duty cycle clock source. All loading with 50  $\Omega$  to  $V_{CC} - 2.0\text{ V}$ .
15. Specification limits represent the amount of delay added with the assertion of each individual delay control pin. The various combinations of asserted delay control inputs will typically realize D0 resolution steps across the specified programmable range.
16. Duty cycle skew guaranteed only for differential operation measured from the cross point of the input to the cross point of the output.
17. This setup time defines the amount of time prior to the input signal the delay tap of the device must be set.
18. This setup time is the minimum time that  $\overline{EN}$  must be asserted prior to the next transition of IN/ $\overline{IN}$  to prevent an output response greater than  $\pm 75\text{ mV}$  to that IN/ $\overline{IN}$  transition.
19. This hold time is the minimum time that  $\overline{EN}$  must remain asserted after a negative going IN or positive going  $\overline{IN}$  to prevent an output response greater than  $\pm 75\text{ mV}$  to that IN/ $\overline{IN}$  transition.
20. This release time is the minimum time that  $\overline{EN}$  must be deasserted prior to the next IN/ $\overline{IN}$  transition to ensure an output response that meets the specified IN to Q propagation delay and transition times.
21. The monotonicity indicates the increasing delay value for each binary count increment on the control inputs D[9:0].



## MC100EP195

An expansion of the latch section of the block diagram is pictured in Figure 7. Use of this diagram will simplify the explanation of how the cascade circuitry works. When D10 of chip #1 in Figure 6 is LOW this device's CASCADE output will also be low while the CASCADE output will be high. In this condition the SET MIN pin of chip #2 will be asserted HIGH and thus all of the latches of chip #2 will be reset and the device will be set at its minimum delay.

Chip #1, on the other hand, will have both SET MIN and SET MAX deasserted so that its delay will be controlled entirely by the address bus A0–A9. If the delay needed is greater than can be achieved with 1023 gate delays

(111111111 on the A0–A9 address bus) D10 will be asserted to signal the need to cascade the delay to the next EP195 device. When D10 is asserted, the SET MIN pin of chip #2 will be deasserted and SET MAX pin asserted resulting in the device delay to be the maximum delay. Table 11 shows the delay time of two EP195 chips in cascade.

To expand this cascading scheme to more devices, one simply needs to connect the D10 pin from the next chip to the address bus and CASCADE outputs to the next chip in the same manner as pictured in Figure 6. The only addition to the logic is the increase of one line to the address bus for cascade control of the second programmable delay chip.

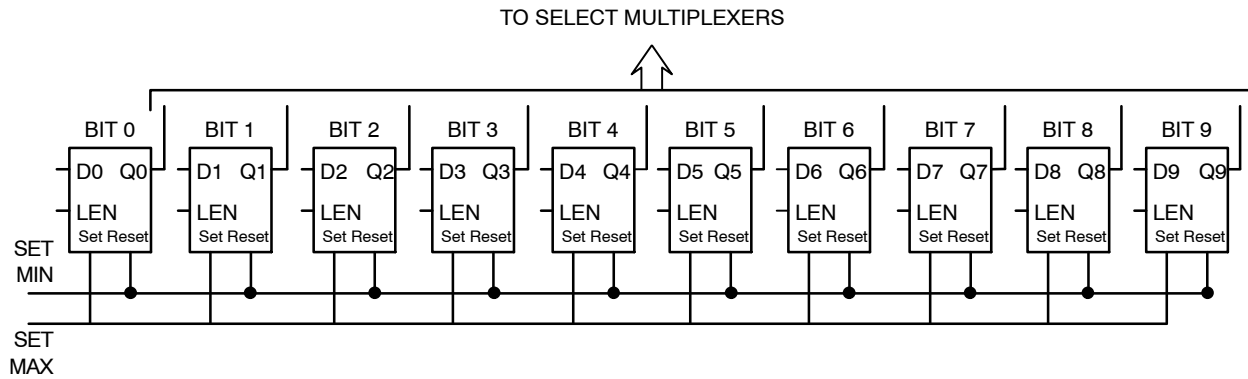


Figure 7. Expansion of the Latch Section of the EP195 Block Diagram

# MC100EP195

**Table 11. Delay Value of Two EP195 Cascaded**

VARIABLE INPUT TO CHIP #1 AND SETMIN FOR CHIP #2												
INPUT FOR CHIP #1											Delay Value	Total Delay Value
D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0		
0	0	0	0	0	0	0	0	0	0	0	0 ps	4400 ps
0	0	0	0	0	0	0	0	0	0	1	10 ps	4410 ps
0	0	0	0	0	0	0	0	0	1	0	20 ps	4420 ps
0	0	0	0	0	0	0	0	0	1	1	30 ps	4430 ps
0	0	0	0	0	0	0	0	1	0	0	40 ps	4440 ps
0	0	0	0	0	0	0	0	1	0	1	50 ps	4450 ps
0	0	0	0	0	0	0	0	1	1	0	60 ps	4460 ps
0	0	0	0	0	0	0	0	1	1	1	70 ps	4470 ps
0	0	0	0	0	0	0	1	0	0	0	80 ps	4480 ps
0	0	0	0	0	0	1	0	0	0	0	160 ps	4560 ps
0	0	0	0	0	1	0	0	0	0	0	220 ps	4720 ps
0	0	0	0	1	0	0	0	0	0	0	640 ps	5040 ps
0	0	0	1	0	0	0	0	0	0	0	1280 ps	5680 ps
0	0	1	0	0	0	0	0	0	0	0	2560 ps	6960 ps
0	1	0	0	0	0	0	0	0	0	0	5120 ps	9520 ps
0	1	1	1	1	1	1	1	1	1	1	10230 ps	14630 ps

VARIABLE INPUT TO CHIP #1 AND SETMAX FOR CHIP #2												
INPUT FOR CHIP #1											Delay Value	Total Delay Value
D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0		
1	0	0	0	0	0	0	0	0	0	0	10240 ps	14640 ps
1	0	0	0	0	0	0	0	0	0	1	10250 ps	14650 ps
1	0	0	0	0	0	0	0	0	1	0	10260 ps	14660 ps
1	0	0	0	0	0	0	0	0	1	1	10270 ps	14670 ps
1	0	0	0	0	0	0	0	1	0	0	10280 ps	14680 ps
1	0	0	0	0	0	0	0	1	0	1	10290 ps	14690 ps
1	0	0	0	0	0	0	0	1	1	0	10300 ps	14700 ps
1	0	0	0	0	0	0	0	1	1	1	10310 ps	14710 ps
1	0	0	0	0	0	0	1	0	0	0	10320 ps	14720 ps
1	0	0	0	0	0	1	0	0	0	0	10400 ps	14800 ps
1	0	0	0	0	1	0	0	0	0	0	10560 ps	14960 ps
1	0	0	0	1	0	0	0	0	0	0	10880 ps	15280 ps
1	0	0	1	0	0	0	0	0	0	0	11520 ps	15920 ps
1	0	1	0	0	0	0	0	0	0	0	12800 ps	17200 ps
1	1	0	0	0	0	0	0	0	0	0	15360 ps	19760 ps
1	1	1	1	1	1	1	1	1	1	1	20470 ps	24870 ps

# MC100EP195

## Multi-Channel Deskewing

The most practical application for EP195 is in multiple channel delay matching. Slight differences in impedance and cable length can create large timing skews within a high-speed system. To deskew multiple signal channels, each channel can

be sent through each EP195 as shown in Figure 8. One signal channel can be used as reference and the other EP195s can be used to adjust the delay to eliminate the timing skews. Nearly any high-speed system can be fine-tuned (as small as 10 ps) to reduce the skew to extremely tight tolerances.

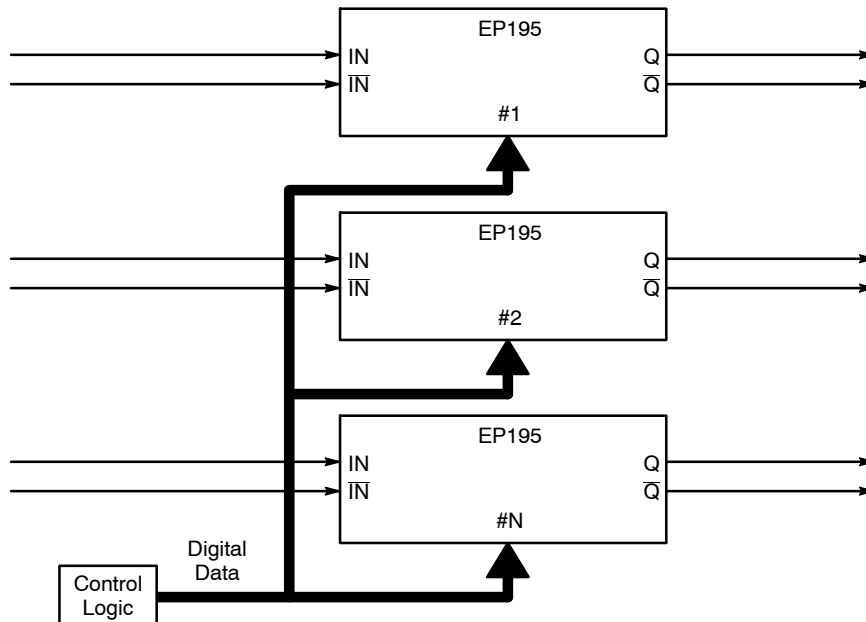


Figure 8. Multiple Channel Deskewing Diagram

## Measure Unknown High Speed Device Delays

EP195s provide a possible solution to measure the unknown delay of a device with a high degree of precision. By combining two EP195s and EP31 as shown in Figure 9, the delay can be measured. The first EP195 can be set to SETMIN and its output is used to drive the input of a D flip-flop of EP31. The second EP195 is triggered along with the first EP195 and its output provides a clock signal for EP31. The programmed delay of the second EP195 is varied to detect the output edge from the unknown delay device.

If the programmed delay through the second EP195 is too long, the flip-flop output will be at logic high. On the other hand, if the programmed delay through the second EP195 is too short, the flip-flop output will be at a logic low. If the programmed delay is correctly fine-tuned in the second EP195, the flip-flop will bounce between logic high and logic low. The digital code in the second EP195 can be directly correlated into an accurate device delay.

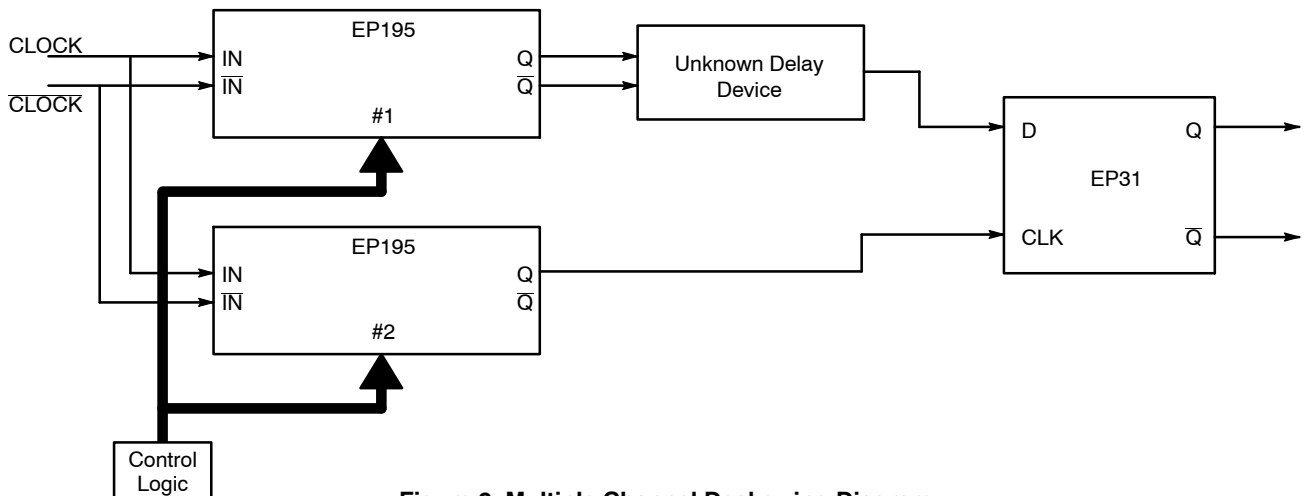
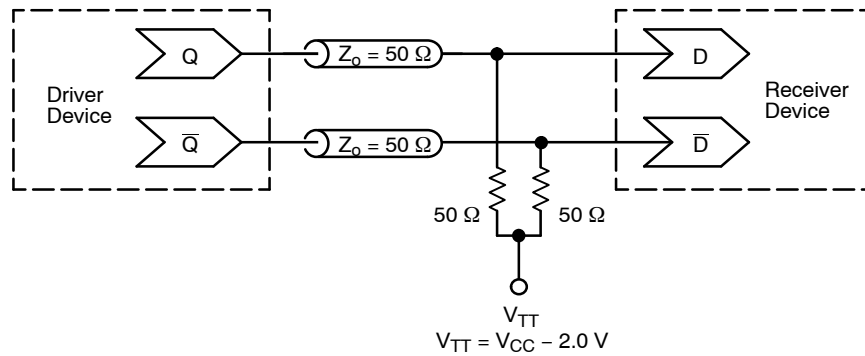


Figure 9. Multiple Channel Deskewing Diagram

## MC100EP195



**Figure 10. Typical Termination for Output Driver and Device Evaluation**  
(See Application Note [AND8020/D](#) – Termination of ECL Logic Devices.)

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC100EP195FAG	LQFP-32 (Pb-Free)	250 Units / Tray
MC100EP195FAR2G	LQFP-32 (Pb-Free)	2000 / Tape & Reel
MC100EP195MNG	QFN-32 (Pb-Free)	74 Units / Tube

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### Resource Reference of Application Notes

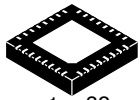
- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPiCE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

ECLinPS is a trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®

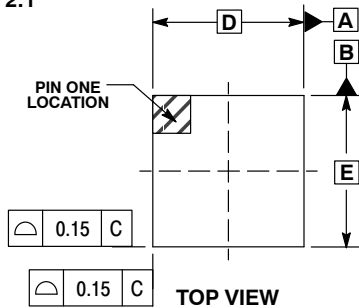


1 32

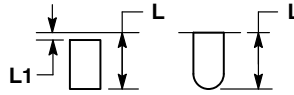
SCALE 2:1

QFN32 5x5, 0.5P  
CASE 488AM  
ISSUE A

DATE 23 OCT 2013



TOP VIEW

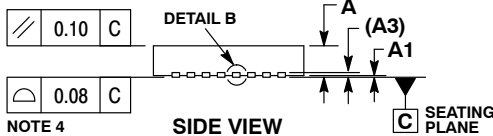


DETAIL A  
ALTERNATE TERMINAL  
CONSTRUCTIONS

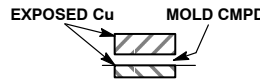
NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30MM FROM THE TERMINAL TIP. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20	REF
b	0.18	0.30
D	5.00	BSC
D2	2.95	3.25
E	5.00	BSC
E2	2.95	3.25
e	0.50	BSC
K	0.20	---
L	0.30	0.50
L1	---	0.15

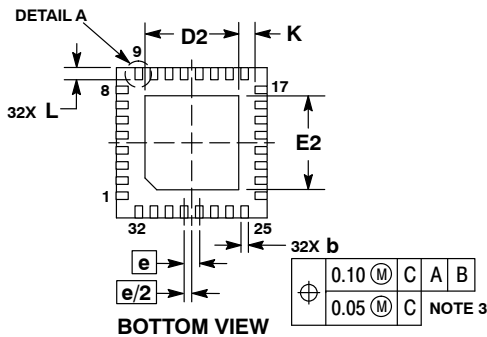


SIDE VIEW

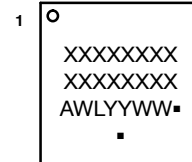


DETAIL B  
ALTERNATE  
CONSTRUCTION

GENERIC  
MARKING DIAGRAM\*



BOTTOM VIEW



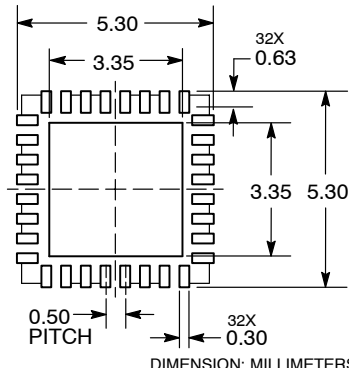
- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED  
SOLDERING FOOTPRINT\*



DIMENSION: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON20032D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	QFN32 5x5 0.5P	PAGE 1 OF 1

ON Semiconductor and ON are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.



**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

ON Semiconductor®



**LQFP-32, 7x7**  
**CASE 561AB-01**  
**ISSUE O**

DATE 19 JUN 2008



SYMBOL	MIN	NOM	MAX
A	—	—	1.60
A1	0.05	—	0.15
A2	1.35	1.40	1.45
B	0.30	0.37	0.45
B1	0.30	0.35	0.40
C	0.09	—	0.20
C1	0.09	—	0.16
D	9.00 BSC		
D1	7.00 BSC		
E	9.00 BSC		
E1	7.00 BSC		
e	0.80 BSC		
L	0.45	0.60	0.75
L1	1.00		
R1	0.08	—	0.20
$\alpha^\circ$	11	—	13
$\beta^\circ$	0	—	7
$\gamma^\circ$	0	—	—



ALL DIMENSIONS IN MM

<b>DOCUMENT NUMBER:</b>	<b>98AON30893E</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>32 LEAD LQFP, 7X7</b>	<b>PAGE 1 OF 1</b>

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

**onsemi**, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

---

## ADDITIONAL INFORMATION

### TECHNICAL PUBLICATIONS:

Technical Library: [www.onsemi.com/design/resources/technical-documentation](http://www.onsemi.com/design/resources/technical-documentation)  
onsemi Website: [www.onsemi.com](http://www.onsemi.com)

### ONLINE SUPPORT: [www.onsemi.com/support](http://www.onsemi.com/support)

For additional information, please contact your local Sales Representative at [www.onsemi.com/support/sales](http://www.onsemi.com/support/sales)